

# DATA SHEET

## **TDA8569Q**

**4 × 40 W BTL quad car radio  
power amplifier**

Product specification  
Supersedes data of 1997 Mar 27

2003 Aug 08

## 4 × 40 W BTL quad car radio power amplifier

## TDA8569Q

### FEATURES

- Capable of driving 2 Ω loads
- Requires very few external components
- High output power
- Low output offset voltage
- Fixed gain
- Diagnostic facility (distortion, short-circuit and temperature pre-warning)
- Good ripple rejection
- Mode select switch (operating, mute and standby)
- Load dump protection
- Short-circuit safe to ground, to  $V_P$  and across the load
- Low power dissipation in any short-circuit condition
- Thermally protected
- Reverse polarity safe

- Electrostatic discharge protection
- No switch-on/switch-off plop
- Flexible leads
- Low thermal resistance
- Pin compatible with the TDA8567Q.

### GENERAL DESCRIPTION

The TDA8569Q is an integrated class-B output amplifier in a 23-lead Single-In-Line (SIL) plastic power package. It contains four amplifiers in Bridge-Tied Load (BTL) configuration, each with a gain of 26 dB. The output power is 4 × 40 W in a 2 Ω load.

### APPLICATIONS

- The device is developed primarily for car radio applications.

### QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_P$	operating supply voltage		6	14.4	18	V
$I_{ORM}$	repetitive peak output current		–	–	7.5	A
$I_{q(tot)}$	total quiescent current		–	230	–	mA
$I_{stb}$	standby current		–	0.2	10	μA
$I_{sw}$	switch-on current		–	–	80	μA
$ Z_i $	input impedance		25	30	–	kΩ
$P_o$	output power	THD = 10%	–	40	–	W
SVRR	supply voltage ripple rejection	$R_s = 0 \Omega$	–	60	–	dB
$\alpha_{cs}$	channel separation	$R_s = 10 \text{ k}\Omega$	–	55	–	dB
$G_v$	closed loop voltage gain		25	26	27	dB
$V_{n(o)}$	noise output voltage	$R_s = 0 \Omega$	–	–	120	μV

### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA8569Q	DBS23P	plastic DIL-bent-SIL power package; 23 leads (straight lead length 3.2 mm)	SOT411-1

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BLOCK DIAGRAM

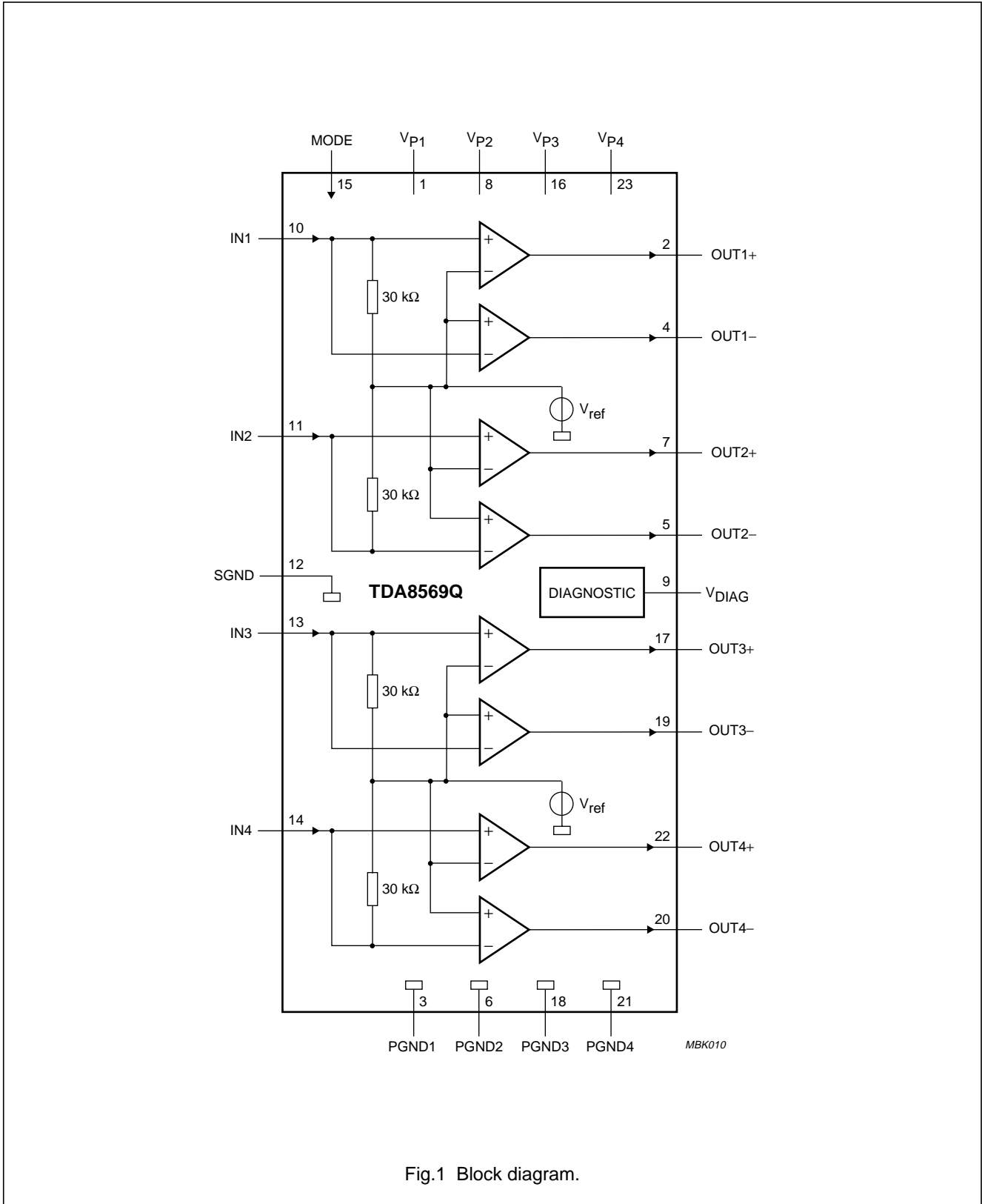


Fig.1 Block diagram.

4 × 40 W BTL quad car radio  
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**PINNING**

SYMBOL	PIN	DESCRIPTION
V <sub>P1</sub>	1	supply voltage 1
OUT1+	2	output 1+
PGND1	3	power ground 1
OUT1-	4	output 1-
OUT2-	5	output 2-
PGND2	6	power ground 2
OUT2+	7	output 2+
V <sub>P2</sub>	8	supply voltage 2
V <sub>DIAG</sub>	9	diagnostic output
IN1	10	input 1
IN2	11	input 2
SGND	12	signal ground
IN3	13	input 3
IN4	14	input 4
MODE	15	mode select switch input
V <sub>P3</sub>	16	supply voltage 3
OUT3+	17	output 3+
PGND3	18	power ground 3
OUT3-	19	output 3-
PGND4	21	power ground 4
OUT4+	22	output 4+
V <sub>P4</sub>	23	supply voltage 4

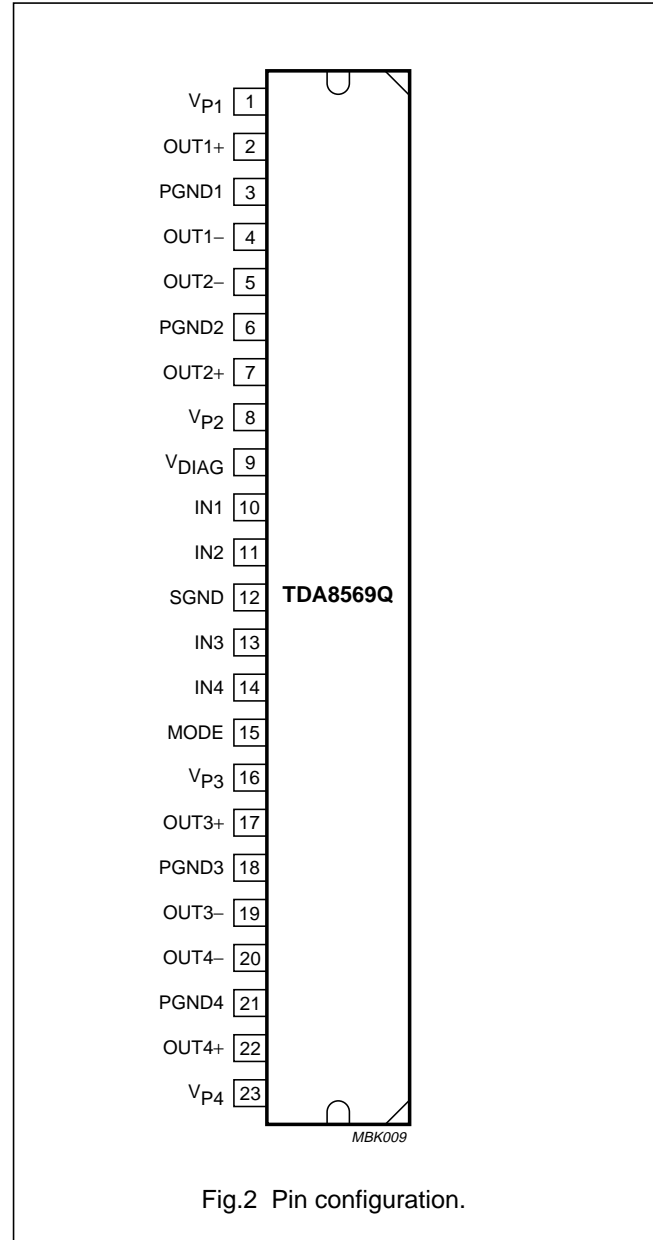


Fig.2 Pin configuration.

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## FUNCTIONAL DESCRIPTION

The TDA8569Q contains four identical amplifiers which can be used for bridge applications. The gain of each amplifier is fixed at 26 dB.

### Mode select switch (pin MODE)

- Standby: low supply current (<100 μA)
- Mute: input signal suppressed
- Operating: normal on condition.

Since this pin has a low input current (<80 μA), a low cost supply switch can be applied.

To avoid switch-on plops, it is advised to keep the amplifier in the mute mode during ≥150 ms (charging of the input capacitors at pins IN1, IN2, IN3 and IN4).

This can be realized by:

- Microprocessor control
- External timing circuit (see Fig.3).

### Diagnostic output (pin V<sub>DIAG</sub>)

#### DYNAMIC DISTORTION DETECTOR (DDD)

At the onset of clipping of one or more output stages, the dynamic distortion detector becomes active and pin V<sub>DIAG</sub> goes LOW. This information can be used to drive a sound processor or DC volume control to attenuate the input signal and so limit the distortion. The output level of pin V<sub>DIAG</sub> is independent of the number of channels that are clipping (see Fig.4).

### SHORT-CIRCUIT DIAGNOSTIC

When a short-circuit occurs at one or more outputs to ground or to the supply voltage, the output stages are switched off until the short-circuit is removed and the device is switched on again, with a delay of approximately 10 ms after removal of the short-circuit. During this short-circuit condition, pin V<sub>DIAG</sub> is continuously LOW.

When a short-circuit occurs across the load of one or more channels, the output stages are switched off for approximately 10 ms. After that time it is checked during approximately 50 μs to determine whether the short-circuit is still present. Due to this duty cycle of 50 μs/10 ms the average current consumption during this short-circuit condition is very low.

During this short-circuit condition, pin V<sub>DIAG</sub> is LOW for 10 ms and HIGH for 50 μs (see Fig.5). The protection circuits of all channels are coupled. This means that if a short-circuit condition occurs in **one** of the channels, **all** channels are switched off. Consequently, the power dissipation in any short-circuit condition is very low.

### TEMPERATURE PRE-WARNING

When the virtual junction temperature T<sub>vj</sub> reaches 145 °C, pin V<sub>DIAG</sub> goes LOW.

### OPEN COLLECTOR OUTPUTS

The diagnostic pin has an open-collector output, so more devices can be tied together. An external pull-up resistor is needed.

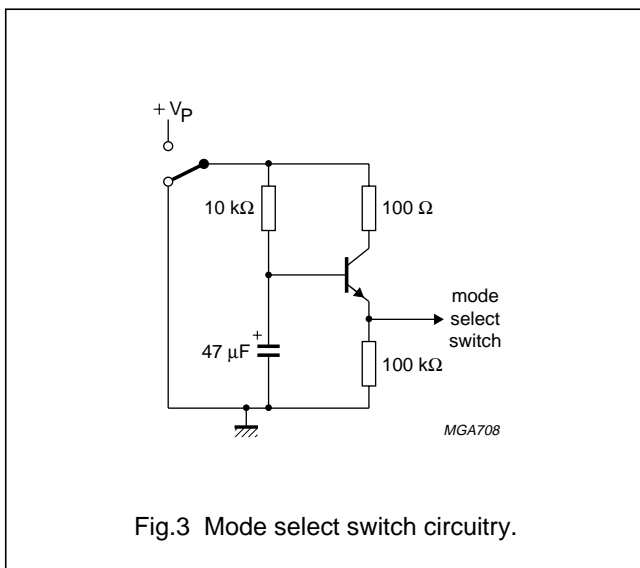


Fig.3 Mode select switch circuitry.

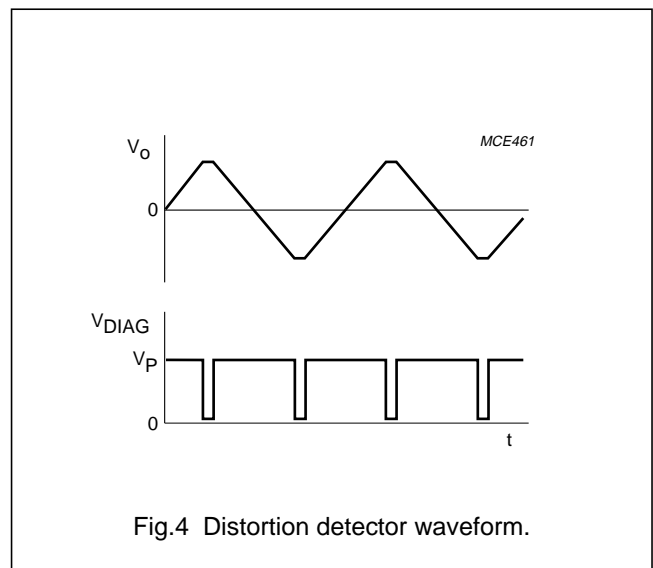


Fig.4 Distortion detector waveform.

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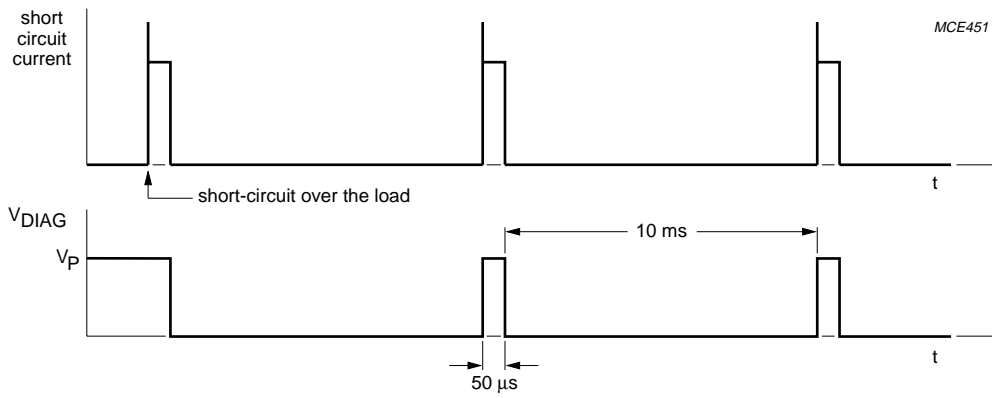


Fig.5 Short-circuit waveform.

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**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>P</sub>	supply voltage	operating	–	18	V
		non-operating	–	30	V
		load dump protection; during 50 ms; t <sub>r</sub> ≥ 2.5 ms	–	45	V
V <sub>sc(safe)</sub>	short-circuit safe voltage		–	18	V
V <sub>rp</sub>	reverse polarity voltage		–	6	V
I <sub>OSM</sub>	non-repetitive peak output current		–	10	A
I <sub>ORM</sub>	repetitive peak output current		–	7.5	A
P <sub>tot</sub>	total power dissipation		–	60	W
T <sub>stg</sub>	storage temperature		–55	+150	°C
T <sub>amb</sub>	ambient temperature		–40	+85	°C
T <sub>vj</sub>	virtual junction temperature		–	150	°C

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient in free air	40	K/W
R <sub>th(j-c)</sub>	thermal resistance from junction to case (see Fig.6)	1	K/W

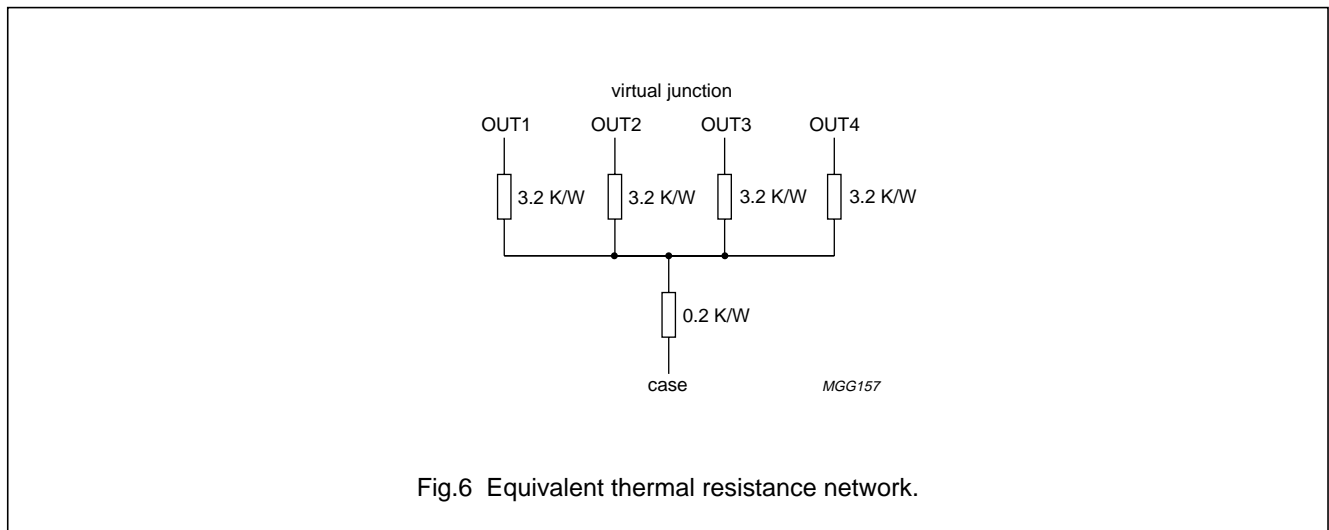


Fig.6 Equivalent thermal resistance network.

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## DC CHARACTERISTICS

$V_P = 14.4\text{ V}$ ;  $T_{\text{amb}} = 25\text{ °C}$ ; measured in Fig.7; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
<b>Supply</b>						
$V_P$	supply voltage	note 1	6	14.4	18	V
$I_{q(\text{tot})}$	total quiescent current	$R_L = \infty$	–	230	360	mA
<b>Operating condition</b>						
$V_{\text{MODE}}$	mode select switch level		8.5	–	$V_P$	V
$I_{\text{MODE}}$	mode select switch current	$V_{\text{MODE}} = 14.4\text{ V}$	–	30	80	$\mu\text{A}$
$V_O$	output voltage	note 2	–	7.0	–	V
$V_{\text{OS}}$	output offset voltage		–	–	150	mV
<b>Mute condition</b>						
$V_{\text{MODE}}$	mode select switch level		3.3	–	6.4	V
$V_O$	output voltage	note 2	–	7.0	–	V
$V_{\text{OS}}$	output offset voltage		–	–	100	mV
$\Delta V_{\text{OS}}$	change of output offset voltage	switching between mute and operating	–	–	100	mV
<b>Standby condition</b>						
$V_{\text{MODE}}$	mode select switch level		0	–	2	V
$I_{\text{stb}}$	standby current		–	0.2	10	$\mu\text{A}$
<b>Diagnostic</b>						
$V_{\text{DIAG}}$	diagnostic output voltage	during any fault condition	–	–	0.6	V
$T_{\text{vj}}$	temperature pre-warning	$V_{\text{DIAG}} = 0.6\text{ V}$	–	145	–	$^{\circ}\text{C}$

## Notes

- The circuit is DC adjusted at  $V_P = 6$  to  $18\text{ V}$  and AC operating at  $V_P = 8.5$  to  $18\text{ V}$ .
- At  $V_P = 18$  to  $30\text{ V}$  the DC output voltage  $\leq \frac{1}{2}V_P$ .



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## AC CHARACTERISTICS

$V_P = 14.4\text{ V}$ ;  $R_L = 2\ \Omega$ ;  $f = 1\text{ kHz}$ ;  $T_{\text{amb}} = 25\text{ °C}$ ; measured in the circuit of Fig.7; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$P_o$	output power	THD = 0.5%	25	30	–	W
		THD = 10%	33	40	–	W
		$V_P = 13.2\text{ V}$ ; THD = 0.5%	–	25	–	W
		$V_P = 13.2\text{ V}$ ; THD = 10%	–	35	–	W
THD	total harmonic distortion	$P_o = 1\text{ W}$	–	0.1	–	%
		$V_{\text{DIAG}} \leq 0.6\text{ V}$ ; note 1	–	10	–	%
$B_p$	power bandwidth	THD = 0.5%; $P_o = -1\text{ dB}$ with respect to 16 W	–	20 to 20000	–	Hz
$f_{\text{ro(l)}}$	low frequency roll-off	at $-1\text{ dB}$ ; note 2	–	25	–	Hz
$f_{\text{ro(h)}}$	high frequency roll-off	at $-1\text{ dB}$	20	–	–	kHz
$G_v$	closed loop voltage gain		25	26	27	dB
SVRR	supply voltage ripple rejection	on; note 3	50	60	–	dB
		mute; note 3	50	60	–	dB
		standby; note 3	80	90	–	dB
$ Z_i $	input impedance		25	30	38	k $\Omega$
$V_{n(o)}$	noise output voltage	on; note 4	–	85	120	$\mu\text{V}$
		on; note 5	–	100	–	$\mu\text{V}$
		mute; note 6	–	60	–	$\mu\text{V}$
$\alpha_{\text{cs}}$	channel separation	note 7	45	55	–	dB
$ \Delta G_v $	channel unbalance		–	–	1	dB
$V_o$	output signal in mute	note 8	–	–	2	mV
$P_o$	output power	THD = 0.5%; $R_L = 4\ \Omega$	–	19	–	W
		THD = 10%; $R_L = 4\ \Omega$	–	25	–	W
$P_{o(\text{EIAJ})}$	EIAJ output power	THD = maximum; square wave input; $V_i = 2\text{ V (p-p)}$	–	40	–	W
THD	total harmonic distortion	$P_o = 1\text{ W}$ ; $R_L = 4\ \Omega$	–	0.05	–	%

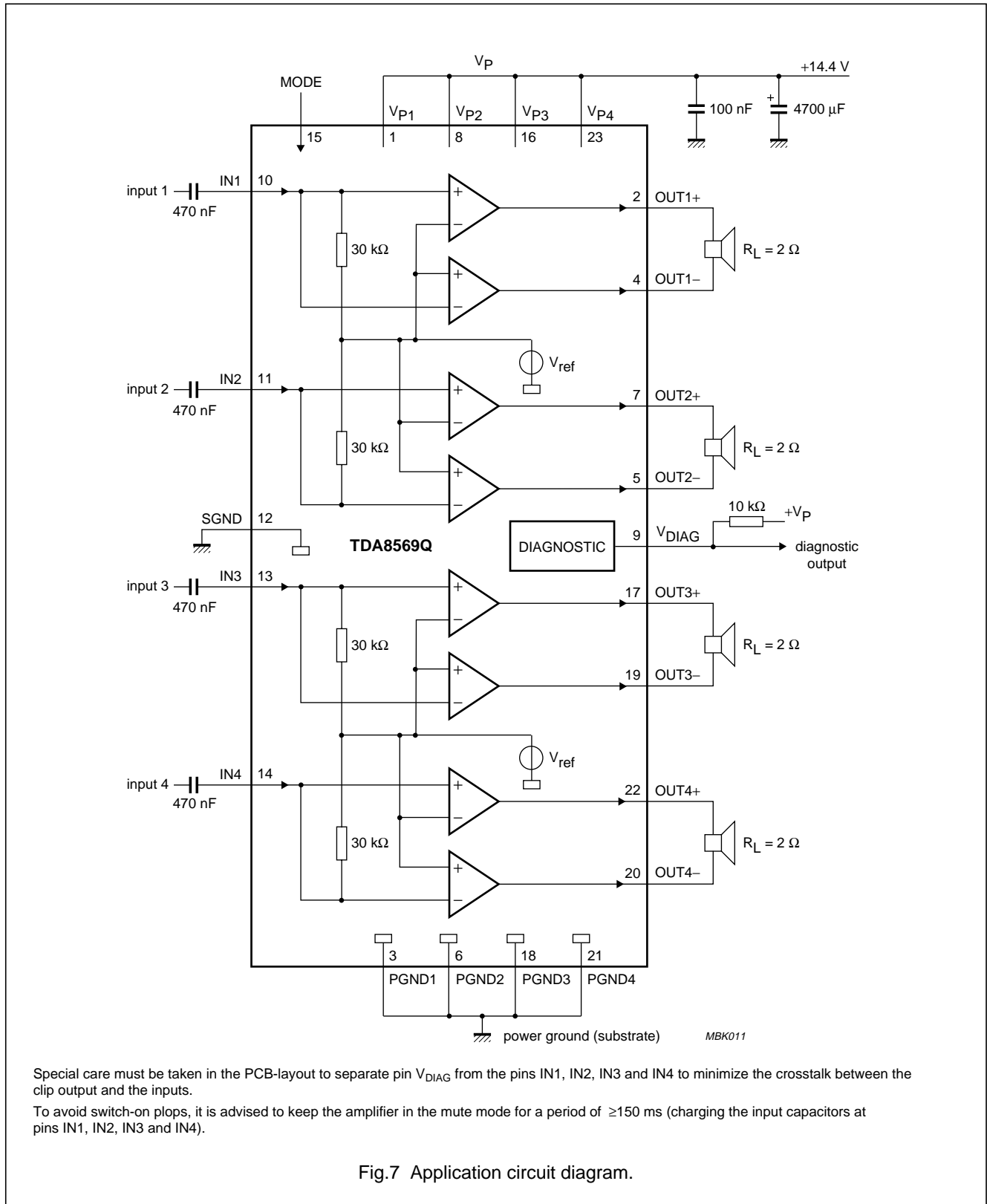
### Notes

- Dynamic Distortion Detector (DDD) active, pin  $V_{\text{DIAG}}$  is set to logic 0.
- Frequency response externally fixed.
- $V_{\text{ripple}} = V_{\text{ripple(max)}} = 2\text{ V (p-p)}$ ;  $R_s = 0\ \Omega$ .
- $B = 20\text{ Hz to }20\text{ kHz}$ ;  $R_s = 0\ \Omega$ .
- $B = 20\text{ Hz to }20\text{ kHz}$ ;  $R_s = 10\text{ k}\Omega$ .
- $B = 20\text{ Hz to }20\text{ kHz}$ ; independent of  $R_s$ .
- $P_o = 25\text{ W}$ ;  $R_s = 10\text{ k}\Omega$ .
- $V_i = V_{i(\text{max})} = 1\text{ V (RMS)}$ .

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TEST AND APPLICATION INFORMATION

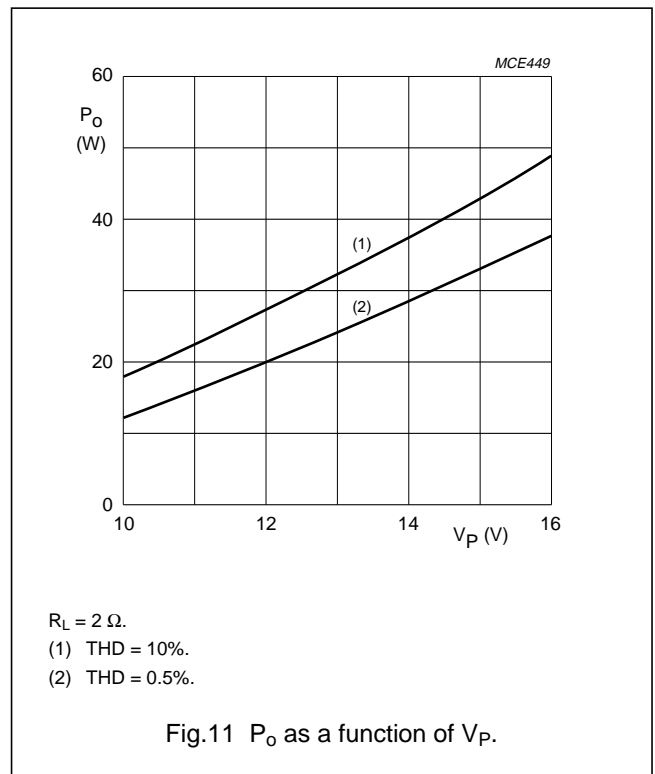
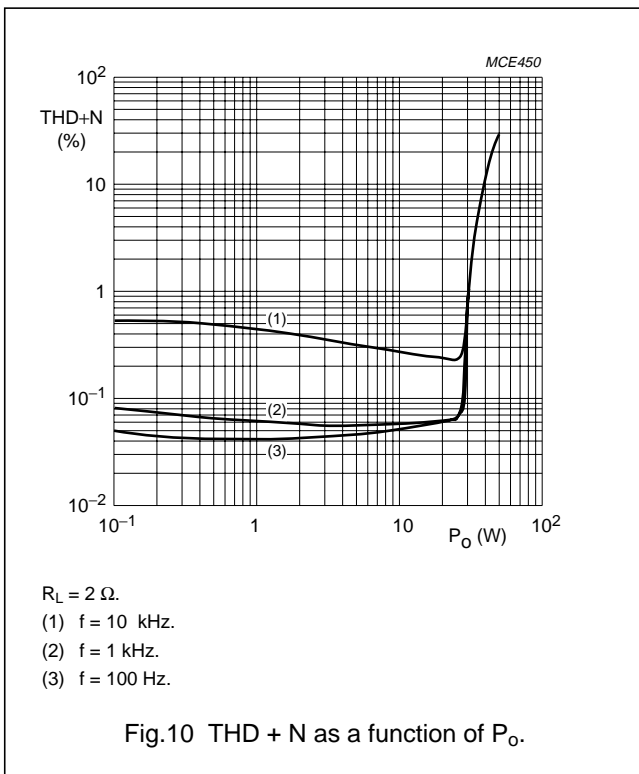
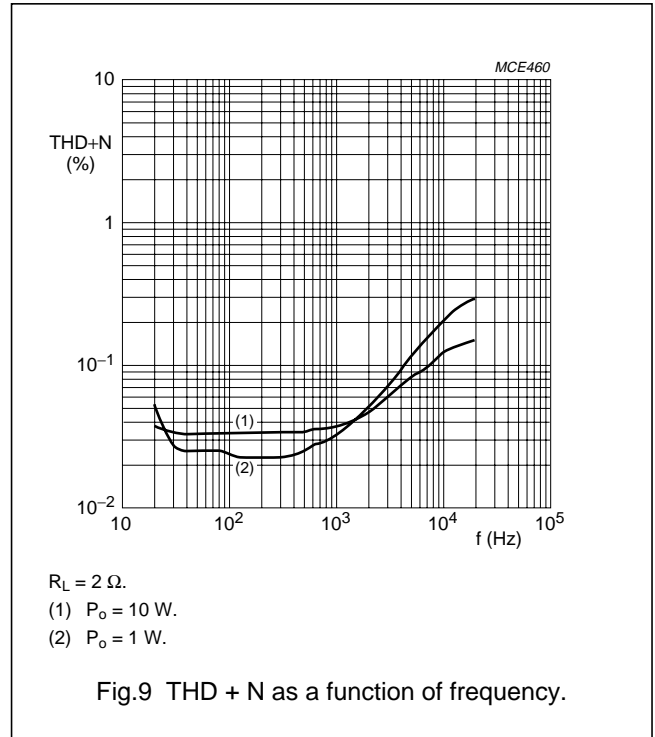
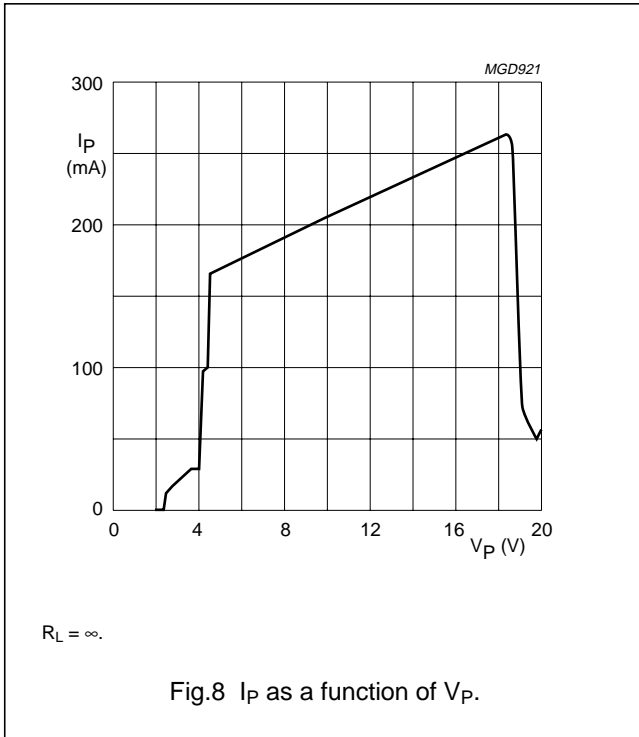


# 4 × 40 W BTL quad car radio power amplifier

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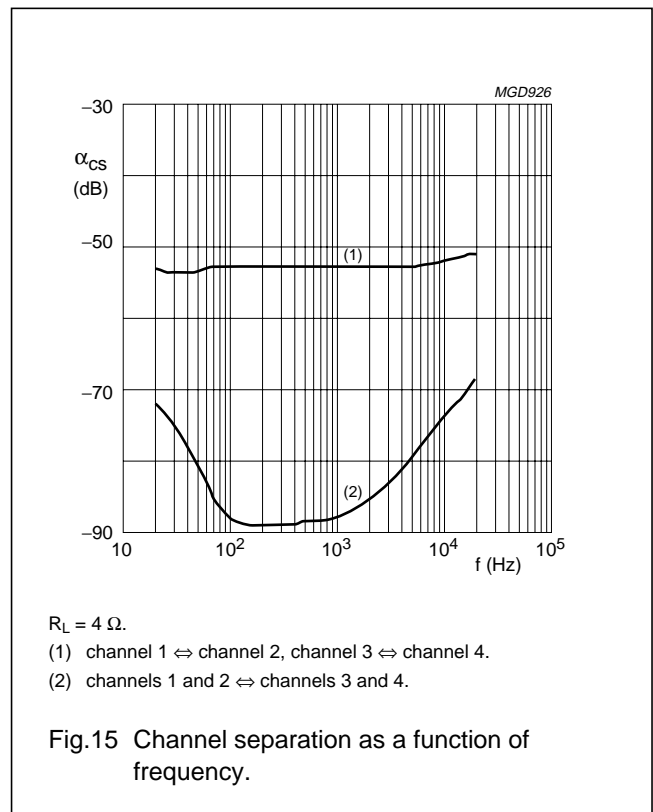
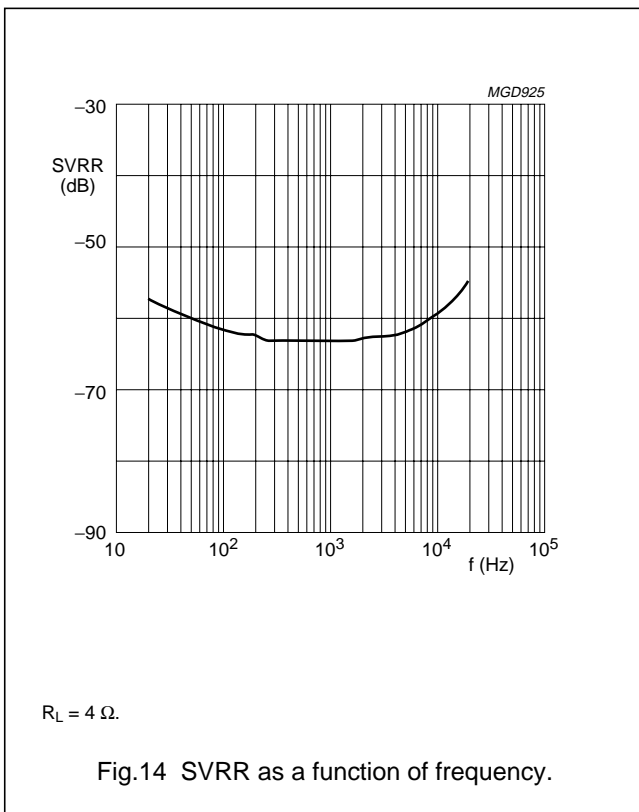
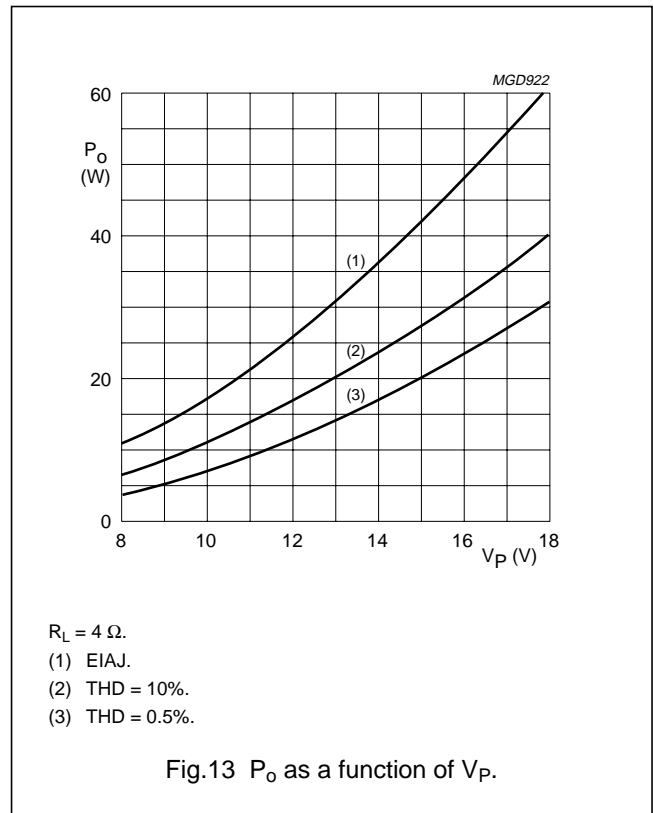
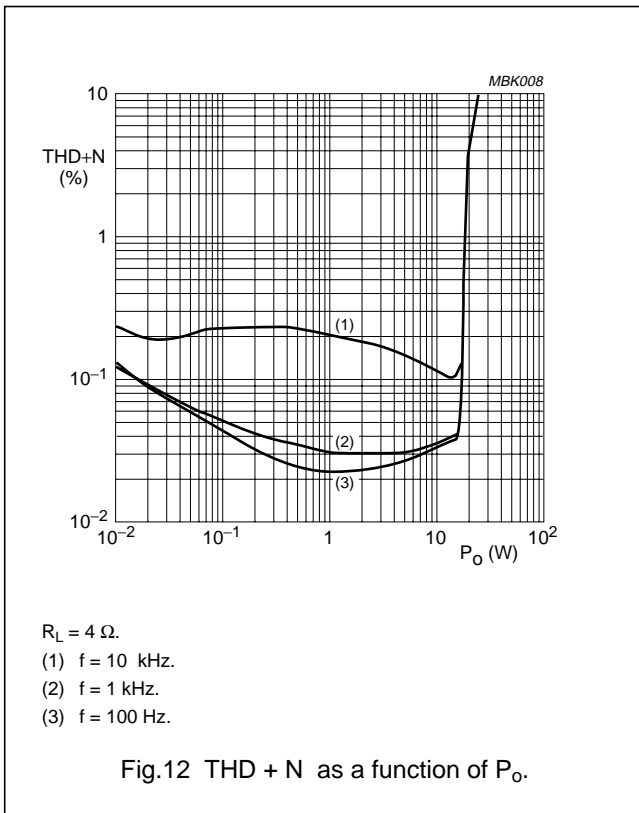
## Test information

Figures 8 to 15 have the following conditions:  $V_P = 14.4\text{ V}$ ;  $f = 1\text{ kHz}$ ; 80 kHz filter used; unless otherwise specified.



4 × 40 W BTL quad car radio power amplifier

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4 × 40 W BTL quad car radio  
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PCB layout

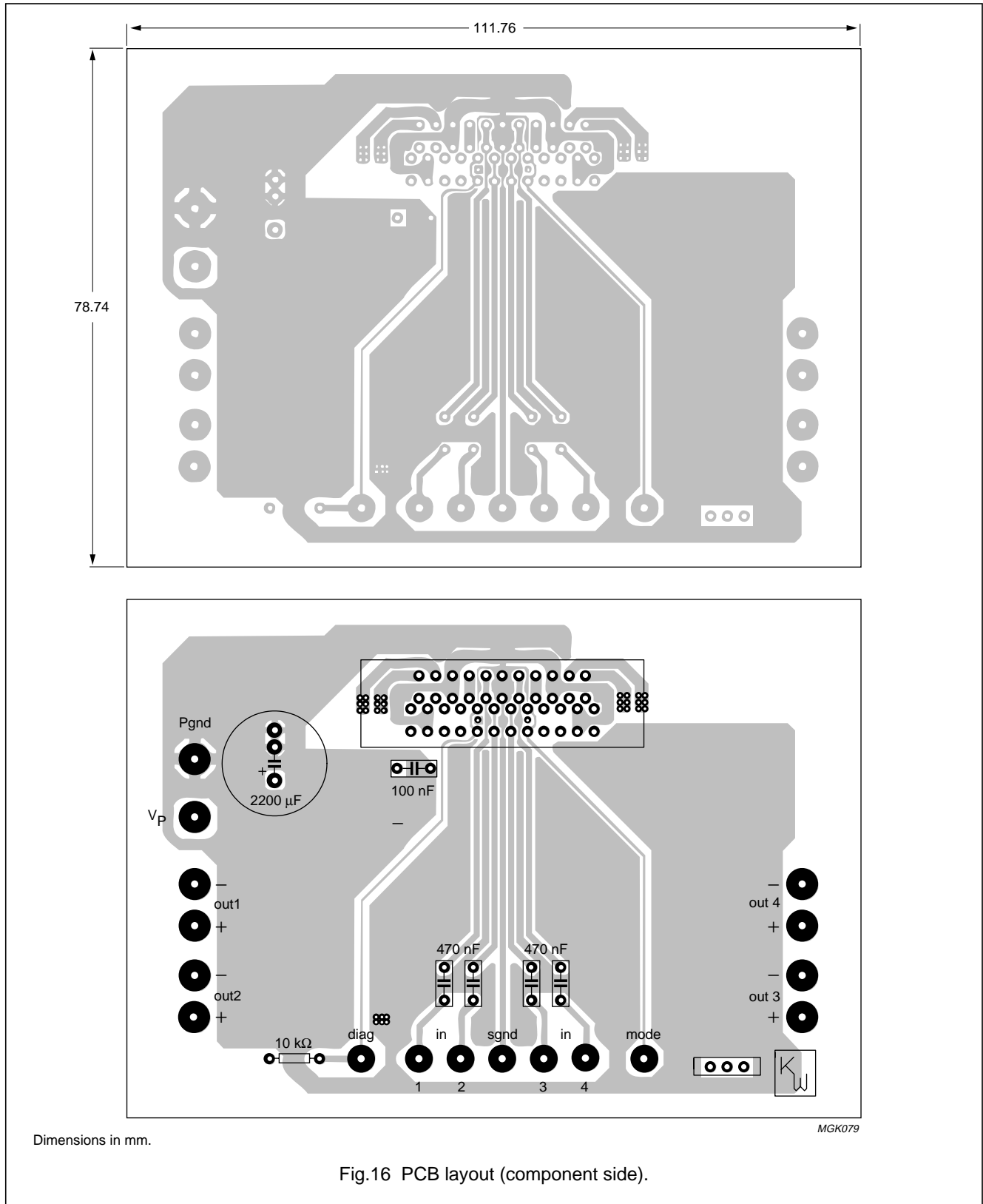
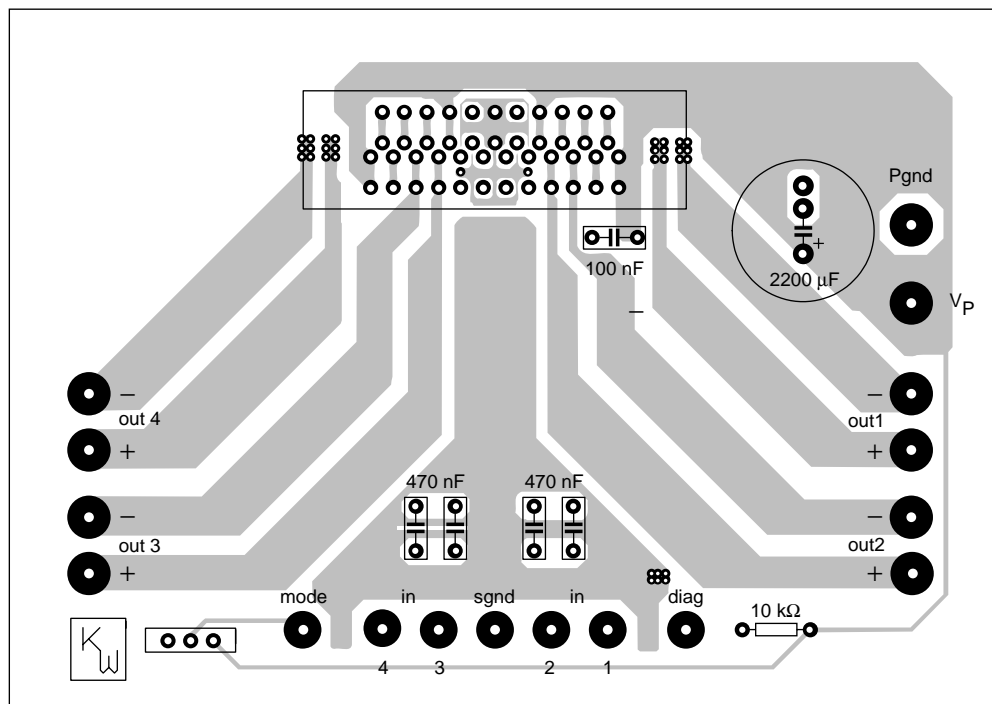
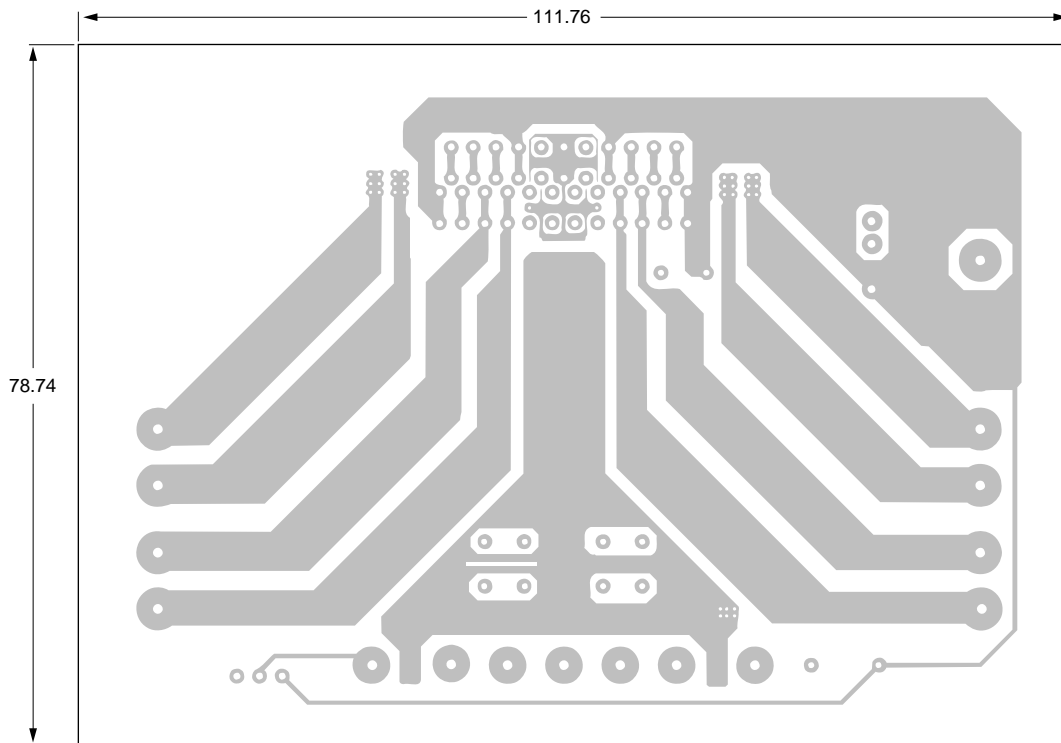


Fig.16 PCB layout (component side).

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Dimensions in mm.

MGK080

Fig.17 PCB layout (soldering side).

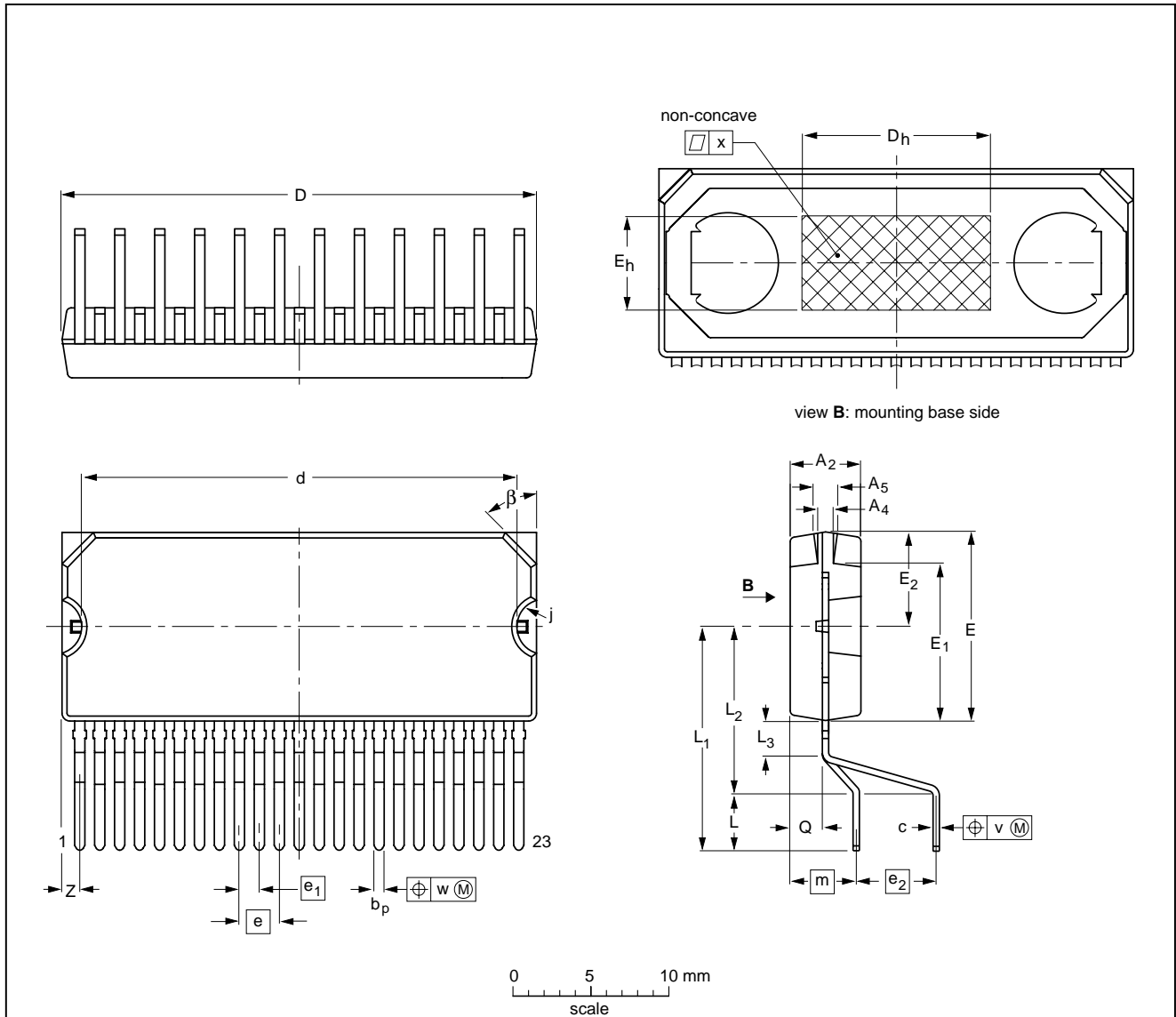
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PACKAGE OUTLINE

DBS23P: plastic DIL-bent-SIL power package; 23 leads (straight lead length 3.2 mm)

SOT411-1



DIMENSIONS (mm are the original dimensions)

UNIT	A <sub>2</sub>	A <sub>4</sub>	A <sub>5</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	d	D <sub>h</sub>	E <sup>(1)</sup>	e	e <sub>1</sub>	e <sub>2</sub>	E <sub>h</sub>	E <sub>1</sub>	E <sub>2</sub>	j	L	L <sub>1</sub>	L <sub>2</sub>	L <sub>3</sub>	m	Q	v	w	x	β	z <sup>(1)</sup>
mm	4.6 4.3	1.15 0.85	1.65 1.35	0.75 0.60	0.55 0.35	30.4 29.9	28.0 27.5	12	12.2 11.8	2.54	1.27	5.08	6	10.15 9.85	6.2 5.8	1.85 1.65	3.6 2.8	14	10.7 9.9	2.4 1.6	4.3	2.1 1.8	0.6	0.25	0.03	45°	1.43 0.78

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT411-1					98-02-20 02-04-24

## 4 × 40 W BTL quad car radio power amplifier

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### SOLDERING

#### Introduction to soldering through-hole mount packages

This text gives a brief insight to wave, dip and manual soldering. A more in-depth account of soldering ICs can be found in our *"Data Handbook IC26; Integrated Circuit Packages"* (document order number 9398 652 90011).

Wave soldering is the preferred method for mounting of through-hole mount IC packages on a printed-circuit board.

#### Soldering by dipping or by solder wave

Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing. Typical dwell time of the leads in the wave ranges from 3 to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ( $T_{stg(max)}$ ). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

#### Manual soldering

Apply the soldering iron (24 V or less) to the lead(s) of the package, either below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

#### Suitability of through-hole mount IC packages for dipping and wave soldering methods

PACKAGE	SOLDERING METHOD	
	DIPPING	WAVE
DBS, DIP, HDIP, SDIP, SIL	suitable	suitable <sup>(1)</sup>

#### Note

- For SDIP packages, the longitudinal axis must be parallel to the transport direction of the printed-circuit board.



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## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.
3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

**Limiting values definition** — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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